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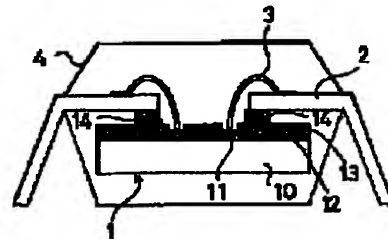
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(54) SEMICONDUCTOR DEVICE

(57) Abstract:

PURPOSE: To obtain an LOC type semiconductor device which does not damage the inside of a semiconductor element at the time of wire bonding.

CONSTITUTION: As to a semiconductor device wherein leads 2 are arranged above a semiconductor element 1, a shock absorber 14 relieving shock to be applied from the leads 2 at the time of wire bonding is formed at least at the parts on a surface protecting film 13 of the semiconductor element 1 with which parts the leads 2 come into contact. When the leads 2 are made to sag by wire bonding and impulsive force is applied to the semiconductor element 1, the impulsive force is transmitted to the inside of the semiconductor element 1 in the state that the impulsive force is relieved by a shock absorber 14. Hence damage is not generated in the inside of the semiconductor element 1.



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